

# P Issac Nelson

## List of Publications by Year in descending order

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Version: 2024-02-01

8  
papers

41  
citations

1937685

4  
h-index

1872680

6  
g-index

8  
all docs

8  
docs citations

8  
times ranked

69  
citing authors

#	ARTICLE	IF	CITATIONS
1	Influence of heat treatment on the properties of thermally evaporated copper selenide thin films. <i>Materials Letters</i> , 2018, 223, 14-16.	2.6	14
2	Curtailed recombination rate and fast carrier transport in ZnPc/GaAs/ZnPc stacked hybrid structure. <i>Optical Materials</i> , 2018, 85, 287-294.	3.6	9
3	Impact of sequential annealing on the characteristics of thermally evaporated semiconductor Cu <sub>2</sub> Se/ZnSe/Cu <sub>2</sub> Se sandwich structure. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 7393-7401.	2.2	8
4	Investigation on the structural, optical and electrical properties of ZnO-Y <sub>2</sub> O <sub>3</sub> (YZO) thin films prepared by PLD for TCO layer applications. <i>AIP Conference Proceedings</i> , 2019, , .	0.4	5
5	Realization of C-60 whiskers incorporated chalcopyrite Cu <sub>1-x</sub> Ga <sub>1-x</sub> Se <sub>2</sub> in Cu <sub>2</sub> Se/C-60/In <sub>3</sub> Se <sub>2</sub> /C-60/Ga <sub>2</sub> Se <sub>3</sub> multilayer structures. <i>Materials Letters</i> , 2021, 282, 128692.	2.6	3
6	Low temperature assisted phase transitions in thermally evaporated Cu <sub>2</sub> Se/Ga <sub>3</sub> Se <sub>2</sub> /In <sub>3</sub> Se <sub>2</sub> multilayer thin film structure: Raman signatures of a pristine chalcopyrite Cu <sub>1-x</sub> Ga <sub>1-x</sub> Se <sub>2</sub> structure. <i>Surfaces and Interfaces</i> , 2022, 29, 101800.	3.0	2
7	Effect of strain in PbSe/ZnPc stacked layers prepared by thermal evaporation method. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 7041-7047.	2.2	0
8	Impact of ZnPc molecular orientation over the transitions in GaAs and its subsequent effects in ZnPc/GaAs stacked thin film structures. <i>Solid State Communications</i> , 2021, 332, 114310.	1.9	0